March 27, **PCN Number:** 20240326001.1 **PCN Date:** 2024 Title: Qualification of alternate mount compound material for select devices **Customer Contact:** Change Management team **Quality Services** Dept: **Sample Requests Proposed 1st Ship Date:** June 25, 2024 April 26, 2024* accepted until: *Sample requests received after April 26, 2024 will not be supported. **Change Type:** Assembly Site Design Wafer Bump Material **Assembly Process** Data Sheet Wafer Bump Process **Assembly Materials** Part number change Wafer Fab Site Mechanical Specification Test Site Wafer Fab Material Packing/Shipping/Labeling Test Process Wafer Fab Process **PCN Details**

Description of Change:

This PCN is to inform of an alternate Mount Compound material set for the list of devices in the product affected sections below.

What	Current	Additional		
Mount Compound	SID#A-09	4226215		

Qualification results are shown below

Reason for Change:

Standardization

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
No Change	No Change		No Change

Changes to product identification resulting from this PCN:

None

Product Affected:

BQ500100DCKR	INA199A3DCKT	OPA180IDBVT	TPS71710DCKT
BQ500100DCKT	INA199B1DCKR	OPA188AIDBVR	TPS71711DCKR
DRV5053CAQDBZR	INA199B1DCKT	OPA188AIDBVT	TPS71711DCKT
DRV5053EAQDBZR	INA199B2DCKR	OPA192IDBVR	TPS71712DCKR
DRV5053OAQDBZR	INA199B2DCKT	OPA192IDBVT	TPS71712DCKT
DRV5053PAQDBZR	INA199B3DCKR	OPA197IDBVR	TPS71713DCKR
DRV5053RAQDBZR	INA199B3DCKT	OPA197IDBVT	TPS71713DCKT
DRV5053VAQDBZR	INA199C1DCKR	OPA377AIDCKR	TPS71715DCKR
INA186A1IDCKR	INA199C1DCKT	OPA377AIDCKT	TPS71715DCKT
INA186A1IDCKT	INA199C2DCKR	TLV333IDCKR	TPS71718DCKR

INA186A2IDCKR	INA210BIDCKR	TLV333IDCKT	TPS71718DCKT
INA186A2IDCKT	INA210BIDCKT	TLV70012DCKR	TPS71719DCKR
INA186A3IDCKR	INA211BIDCKR	TLV70012DCKT	TPS71719DCKT
INA186A3IDCKT	INA211BIDCKT	TLV70015DCKR	TPS71721DCKR
INA186A4IDCKR	INA211CIDCKR	TLV70015DCKT	TPS71721DCKT
INA186A4IDCKT	INA212AIDCKR	TLV70018DCKR	TPS71725DCKR
INA186A5IDCKR	INA212AIDCKT	TLV70018DCKT	TPS71725DCKT
INA190A1IDCKR	INA212BIDCKR	TLV70025DCKR	TPS71726DCKR
INA190A1IDCKT	INA212CIDCKR	TLV70025DCKT	TPS71726DCKT
INA190A2IDCKR	INA213BIDCKR	TLV70028DCKR	TPS71727DCKR
INA190A2IDCKT	INA213BIDCKT	TLV70028DCKT	TPS71727DCKT
INA190A3IDCKR	INA213CIDCKR	TLV70030DCKR	TPS717285DCKR
INA190A3IDCKT	INA213CIDCKT	TLV70030DCKT	TPS717285DCKT
INA190A4IDCKR	INA214BIDCKR	TLV70033DCKR	TPS71728DCKR
INA190A4IDCKT	INA214BIDCKT	TLV70033DCKT	TPS71728DCKT
INA190A5IDCKR	INA215AIDCKR	TMP126DCKR	TPS71729DCKR
INA190A5IDCKT	INA215AIDCKT	TMP126NDCKR	TPS71729DCKT
INA199A1DCKR	INA215BIDCKR	TPS62260DDCR	TPS71730DCKR
INA199A1DCKT	INA215BIDCKT	TPS71701DCKR	TPS71730DCKT
INA199A2DCKR	INA215CIDCKR	TPS71701DCKT	TPS71733DCKR
INA199A2DCKT	OPA180IDBVR	TPS71710DCKR	TPS71733DCKT
INA199A3DCKR	TPS62561DDCR		

TI Information Selective Disclosure

Qualification Report Approve Date 01-MARCH -2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: OPA328DBVT	QBS Reference: OPA1671IDCKR	QBS Reference: OPA2328DGKR	QBS Reference: OPA3S328RGRR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	1/77/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	1/77/0	3/231/0
TC	A4	Temperature Cycle	-65/150C	500 Cycles	-	3/231/0	1/77/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	1/77/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-		3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0	3/231/0	1/77/0	-
HTOL	B1	Life Test	150C	300 Hours		3/231/0	1/77/0	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2397/01	-	-
SD	С3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB Solder;		3/66/0	-		-
SD	С3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	3/66/0	-	-	-

PD	C4	Physical Dimensions	(per mechanical drawing)	-	3/15/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	3/9/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	3/9/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/6/0	3/18/0	1/6/0	3/18/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	1/30/0	3/90/0

- . OBS: Oual By Similarity
- . Qual Device OPA328DBVT is qualified at MSL1 260C
- · Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: R-NPD-2206-042

[1]-Lost 3 units.

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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